

Semiconductor devices - Mechanical and climatic test methods - Part 15: Resistance to soldering temperature for through-hole mounted devices

EESTI STANDARDI EESSÕNA

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See Eesti standard EVS-EN IEC 60749-15:2020 sisaldab Euroopa standardi EN IEC 60749-15:2020 ingliskeelset teksti.	This Estonian standard EVS-EN IEC 60749-15:2020 consists of the English text of the European standard EN IEC 60749-15:2020.
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English Version

**Semiconductor devices - Mechanical and climatic test methods -
Part 15: Resistance to soldering temperature for through-hole
mounted devices
(IEC 60749-15:2020)**

Dispositifs à semiconducteurs - Méthodes d'essais
mécaniques et climatiques - Partie 15: Résistance à la
température de brasage pour dispositifs par trous
traversants
(IEC 60749-15:2020)

Halbleiterbauelemente - Mechanische und klimatische
Prüfverfahren - Teil 15: Beständigkeit gegen Löttemperatur
bei Bauelementen zur Durchsteckmontage
(IEC 60749-15:2020)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

The text of document 47/2630/FDIS, future edition 3 of IEC 60749-15, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60749-15:2020.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2021-05-18
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2023-08-18

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-20	-	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	-	-
IEC 60749-3	-	Semiconductor devices - Mechanical and climatic test methods - Part 3: External visual examination	EN 60749-3	-
IEC 60749-8	-	Semiconductor devices - Mechanical and climatic test methods - Part 8: Sealing	EN 60749-8	-

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Semiconductor devices – Mechanical and climatic test methods –
Part 15: Resistance to soldering temperature for through-hole mounted devices**

**Dispositifs à semiconducteurs – Méthodes d'essais mécaniques
et climatiques –
Partie 15: Résistance à la température de brasage pour dispositifs par trous
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –****Part 15: Resistance to soldering temperature
for through-hole mounted devices**

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International Standard IEC 60749-15 has been prepared by IEC technical committee 47: Semiconductor devices.

This third edition cancels and replaces the second edition published in 2010. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) inclusion of new Clause 3, Terms and definitions;
- b) clarification of the use of a soldering iron for producing the heating effect;
- c) inclusion an option to use accelerated ageing.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47/2630/FDIS	47/2639/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60749 series, published under the general title *Semiconductor devices – Mechanical and climatic test methods*, can be found on the IEC website.

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